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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.		
10/777,189	02/13/2004	Shigetoshi Wakayama	042107 8258			
38834 7:	38834 7590 11/06/2006			EXAMINER		
	N, HATTORI, DANIEI	PHAM, I	PHAM, HOAI V			
	CTICUT AVENUE, NW	ART UNIT	PAPER NUMBER			
SUITE 700 WASHINGTO	N, DC 20036	2814				
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Please find below and/or attached an Office communication concerning this application or proceeding.

		Application N		Applicant(s)				
Office Action Summary			, , ,					
		10/777,189		WAKAYAMA ET AI	L.			
		Examiner		Art Unit				
		Hoai v. Pham		2814				
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply								
THE I - Exter after - If the - If NO - Failu Any r	ORTENED STATUTORY PERIOD FOR REPLY MAILING DATE OF THIS COMMUNICATION. Insions of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication. Period for reply specified above is less than thirty (30) days, a reply period for reply is specified above, the maximum statutory period were to reply within the set or extended period for reply will, by statute, eply received by the Office later than three months after the mailing and patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, he y within the statutory will apply and will expi , cause the applicatio	owever, may a reply be tim minimum of thirty (30) days re SIX (6) MONTHS from t n to become ABANDONED	ely filed will be considered timely, the mailing date of this con (35 U.S.C. § 133).	mmunication.			
Status								
1)⊠	Responsive to communication(s) filed on 29 Se	eptember 2006						
2a) ☐	This action is FINAL . 2b)⊠ This action is non-final.							
3) 🗌								
	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.							
Disposition of Claims								
5)□ 6)⊠ 7)□	4) Claim(s) 1-15 is/are pending in the application. 4a) Of the above claim(s) 5 and 7-15 is/are withdrawn from consideration. 5) Claim(s) is/are allowed. 6) Claim(s) 1-4 and 6 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or election requirement.							
Applicati	on Papers							
10)	The specification is objected to by the Examine The drawing(s) filed on is/are: a) _ according a content of the Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct The oath or declaration is objected to by the Example 1.	epted or b) c drawing(s) be he tion is required if	eld in abeyance. See the drawing(s) is obj	e 37 CFR 1.85(a). ected to. See 37 CF				
Priority u	ınder 35 U.S.C. § 119							
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 								
	t(s) e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948)	4) [☐ Interview Summary Paper No(s)/Mail Da	ite				
3) 🔲 Inform	nation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) r No(s)/Mail Date	· · · · · · · · · · · · · · · · · · ·	Notice of Informal Pa	atent Application (PTO	·-152)			

Application/Control Number: 10/777,189 Page 2

Art Unit: 2814

DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

2. Claims 1-4, 6 are rejected under 35 U.S.C. 102(e) as being anticipated by Usui [U.S. 2005/0082577] previously applied.

With respect to claim 1, Usui (figs. 6-7, col. 3-4) discloses a semiconductor device, comprising:

semiconductor substrate (11); and

a multilayer interconnection structure formed on said substrate, said multilayer interconnection structure comprising:

a first guard ring (21) extending continuously in said multilayer interconnection structure along periphery of said semiconductor substrate; and

a second guard ring (21) extending continuously in said multilayer interconnection structure along said periphery so as to be encircled by said first guard ring, said second guard ring encircling an interconnection pattern inside said multilayer interconnection structure;

Art Unit: 2814

said first and second guard rings (21) being connected with each other mechanically and continuously by a bridging conductor pattern (22) extending continuously in a band form along a region including said first and second guard rings, when viewed in the direction perpendicular to a principal surface of said semiconductor substrate.

With respect to claim 2, Usui discloses that wherein said bridging conductor pattern (22) does not have any of a gap or an opening (fig. 6).

With respect to claim 3, Usui discloses that wherein said bridging conductor pattern (22) is provided at plural different positions having different heights as measured from a surface of said semiconductor substrate (fig. 6).

With respect to claim 4, Usui discloses that wherein said bridging conductor pattern (22) is formed in one or more interlayer insulation films (15) in said multilayer interconnection structure.

With respect to claim 6, Usui discloses that wherein said multilayer interconnection structure has a layered structure in which a plurality of interlayer insulation films (15) each including an interconnection layer corresponding thereto are stacked, and wherein an interconnection layer formed in one interlayer insulation film of said plural interlayer insulation films is connected to an underlying interconnection layer

Application/Control Number: 10/777,189 Page 4

Art Unit: 2814

by a via-plug (23), each of said first and second guard rings having a layered structure identical to that of said multilayer interconnection structure, said bridging conductor pattern being formed at a height identical to that of the interconnection layer in said interlayer insulation film in which said bridging conductor pattern is formed (fig. 6).

Response to Arguments

3. Applicant's arguments with respect to claims 1-4 and 6 have been considered but are most in view of the new ground(s) of rejection.

Conclusion

- 4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Hoai v. Pham whose telephone number is 571-272-1715. The examiner can normally be reached on M-F.
- 5. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael M. Fahmy can be reached on 571-272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Application/Control Number: 10/777,189

Art Unit: 2814

Page 5

6. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

HOAI PHAM
PRIMARY EXAMINER